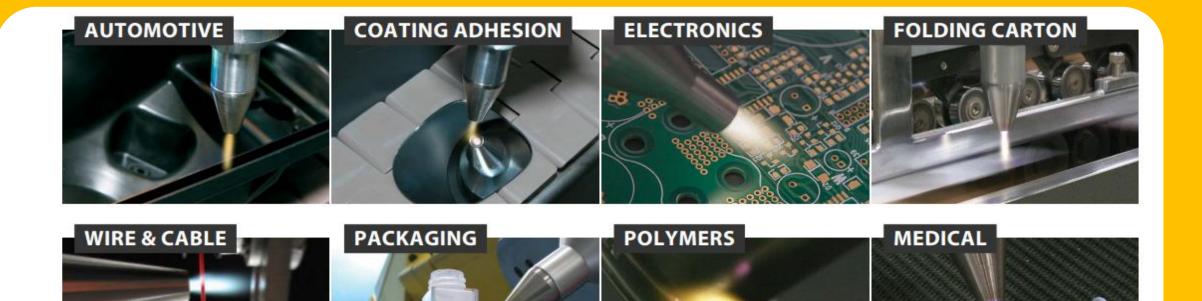
2022 Surface Treating Representative Meeting





262.255.6070 / www.enerconind.com/treating

262.255.6070 / www.enerconind.com/treating

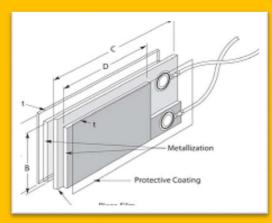
AİS Target Markets

- Electronics
- Printing
- Wire and Cable
- Automotive
- Aerospace
- Consumer Products
- Packaging
- Windows and Doors
- General Manufacturing

Electronics

Applications

- Lead Frames electroplating
- Cleaning Semiconductors
- Remove oxide layers, solder flux and glue
- Component level cleaning
- Bonding electronic parts
- PCB
- LCD Display



Piezoelectric Sensor



Junction Box - bonding



Glass/frame bonding



Lead Frames

LCD Displays



Printing/Painting

Applications

- Printing on aluminum
- Printing on Plastic
- Wire and Tubing HDPE Pipe and Conduit
- Fiber Optic Cable and Wire
- Closures and Bottles
- Natural Gas



Printing on Wire/Tubing



Automative





Packaging

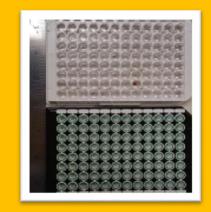
Medical

Applications

- Cleaning lab slides
- cathaters
- Bonding dissimilar materials
- Cleaning glass/plastic components
- Cleaning Activating tubing
- Coating Filters (low pressure)
- Removing organics/bio-contaminants
- Bonding SS to Polypropylene (needles)
- Disinfecting



Glass slides



Test trays



Balloon/cathater



Glass disc



Plastic tubing

Catheters

Wire and Cable

Applications

- Printing on jacket
- Activation prior to coating
- Cleaning Aluminum/Copper prior to jacket



Automotive

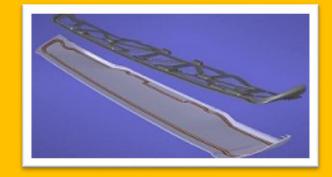
Applications

- Lightweight Vehicles
- Aluminum engine block and transmission
- Composites bonding
- Door seal
- Eliminate metal fasteners
- Headlamps
- Structural bonding truck cargo trailer
- Automotive Injection Molded Parts



dashboard





Door seal

Car Spoiler

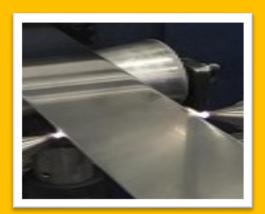
Aerospace

Applications

- Window bonding
- Composite Bonding
- Carbon Fiber Reinforced Plastic (CFRP)
- Remove dust and static before bonding
- Eliminate organics before bonding
- Pretreatment for Welding



Window bonding





Welding Prep

Wing assemblies

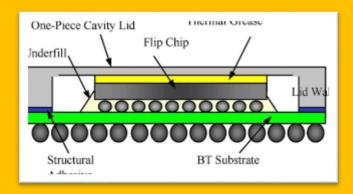
Composites bonding

Consumer Products/Electronics

Applications

- Flooring
- Cell phone cover activations
- PCB cleaning and activation
- Circuit board chip manufacturing
- Flip Chip
- Doors and Windows







flooring

Flip chip

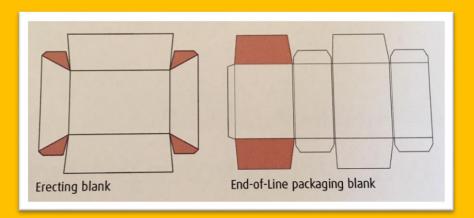
Packaging

Applications

- Roll to roll Al for cans
- Adhesive lines for box
- Fold and Glue box



Roll to roll Aluminum





Box/Packaging

Window and Door

Applications

- Glass to Aluminum
- Glass to plastic
- Joint bonding for frames
- Clean glass prior to coatings







General Manufacturing

Applications

- Thin Wall Tubing
- Welding Applications improve strength
- Graphene remove organics from copper
- Window Blinds
- Solar Cells
- 3D printing coating and Z axis
- Appliances



Welding



Aluminum Tubing



Copper Cleaning



Solar cells/junction box



Window blinds



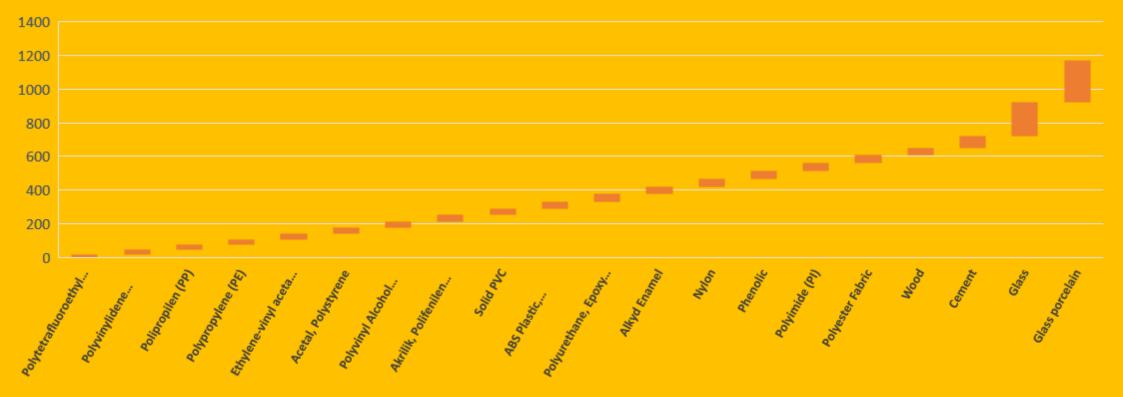
3D printing





Surface Energy of Meterials

🔳 Artış 📕 Düşüş 📕 Toplam



Surface Treatment Plastics Typical Starting Dynes

Material	Initial Dyne Level	Post Treatment Dyne Level	Material	Initial Dyne Level	Post Treatment Dyne Level
ABS	31-35	44-72	Polycarbonate	37	56-72
ETFE	30>	50	Polyethylene	32-34	42-60+
ETFE	30>	50	Polypropylene	30-34	45-60
Flexible PVC	33-36	40-56	Polystyrene	36	52-70
PEEK	30	>72	PTFE	30>	50
PET	35	44-60	Rigid PVC	33-36	42-60+
			TPU	34	48

Several factors can impact initial and post treatment dyne level readings. The chart above is provided as a general guideline of typical results.

Plasma-Generated Adhesion

Depending on the material to be treated and the nature of the plasma gas, several mechanisms contribute to adhesion:

- Surface Activation: Plasma activation has a large mechanical effect, continuously removing single atoms from surfaces.
- Density of Functional Groups: Adhesion strength can be linearly aligned to functional group density.
- Free Radical Effect: Remaining radical sites highly reactive and promote adhesion of inks, coating and adhesives.
- Increased Polarity: Reactive gases added to the plasma activation process can deliver new surface functionalities which reverse polarity of materials, such as polypropylene.
- High Wettability: After plasma activation, aqueous solutions with high surface tension spread on the activated surface, showing very small contact angles.
- Reductive Chemistry: On foils, surface oxide layers form within minutes. Plasma activation with hydrogen-containing plasma gas reduces superficial oxide layers to improve foil surfaces for bonding.

